

Selection Guide

Part No.	Dice	lens type	IV(mcd)@20mA		Viewing Angle
			Min	Typ	2θ _{1/2}
FYLS-3528URC	Red(Gap)	Water clear	310	460	120

Electrical/Optical Characteristics at Ta=25 °c

Symbol	Parameter	Device	min.	typ.	units	test conditions
λd	Dominate wavelength	Red	621	625	nm	IF=20mA
VF	Forward Voltage	Red	1.6	2.0	V	IF=20mA
IR	Reverse Current	Red		5	μA	VR=5V

Absolute Maximum Ratings At= 25 °c

Parameter	White	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current(1)	185	mA
Reverse Voltage	5	V
Operating/storage Temperature	-40°C to +85°C	

Note:

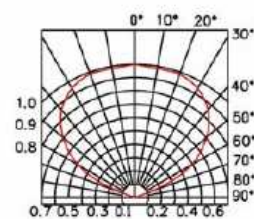
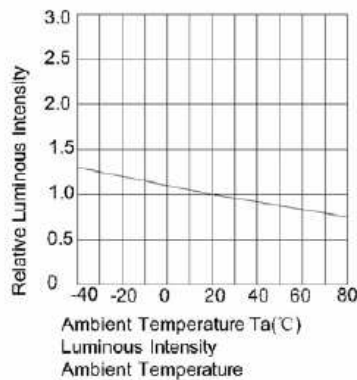
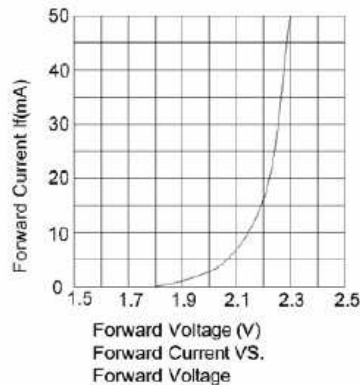
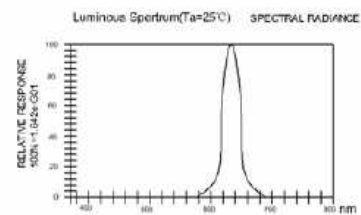
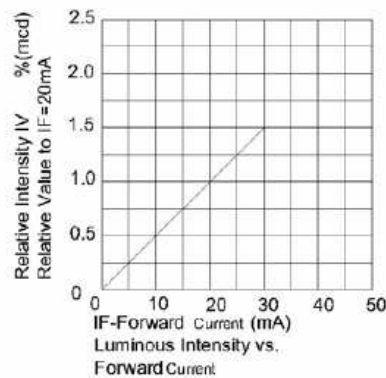
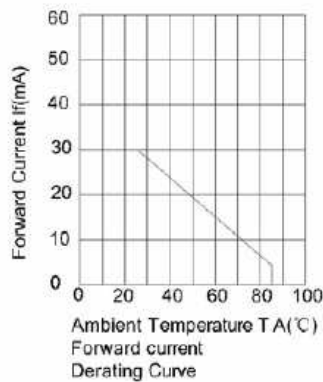
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

Reliability Test items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level:90% LTPD:10%

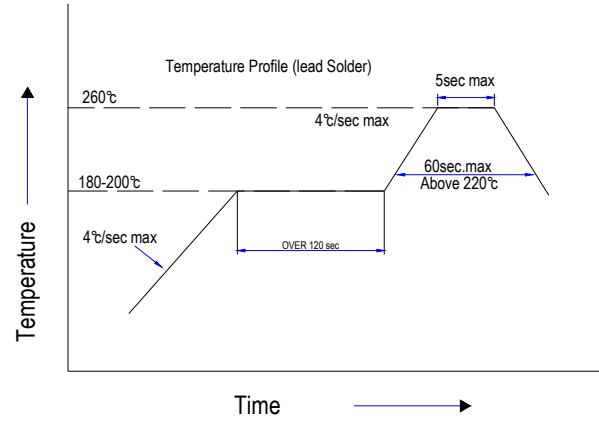
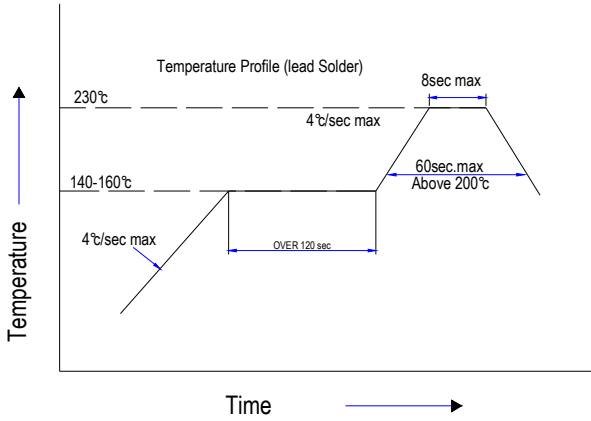
NO.	Items	test condition	test Hours/Cycles	sample Size	Ac/Rc
1	Reflow	Temp:240°C ± 5°C Min:5sec	6Min	22pcs	0/1
2	Temperature cycle	H: +100°C 15min.~5min L:-40°C~ 15min	300 Cycles	22pcs	0/1
3	Thermal shock	H: +100°C 5min.~10sec. L:-10°C 5min	300 Cycles	22pcs	0/1
4	High Temperature Storage	temp:100°C	1000hrs.	22pcs	0/1
5	LOW Temperature Storage	temp:-55°C	1000hrs.	22pcs	0/1
6	DC Operating Life	IF=20mA	1000hrs.	22pcs	0/1
7	High Temperature /High Humidity	85°C/R,H80%	1000hrs.	22pcs	0/1



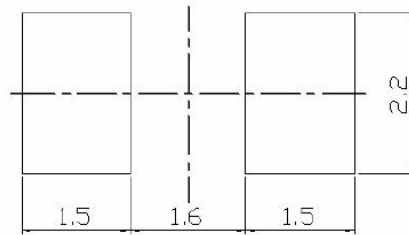
SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling

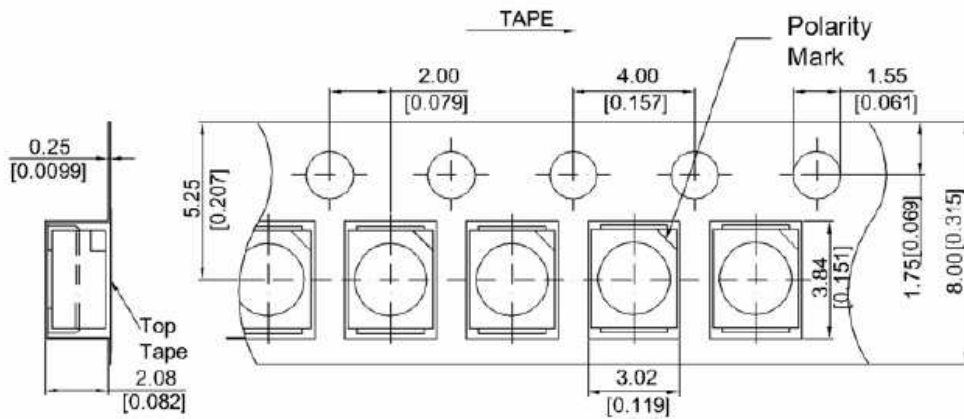
Process to normal temperature is required between first and second soldering process



Recommended Soldering Pattern(Units:mm)



Tape Specifications (Units : mm)



◆ Packing and Shipping Spec.

